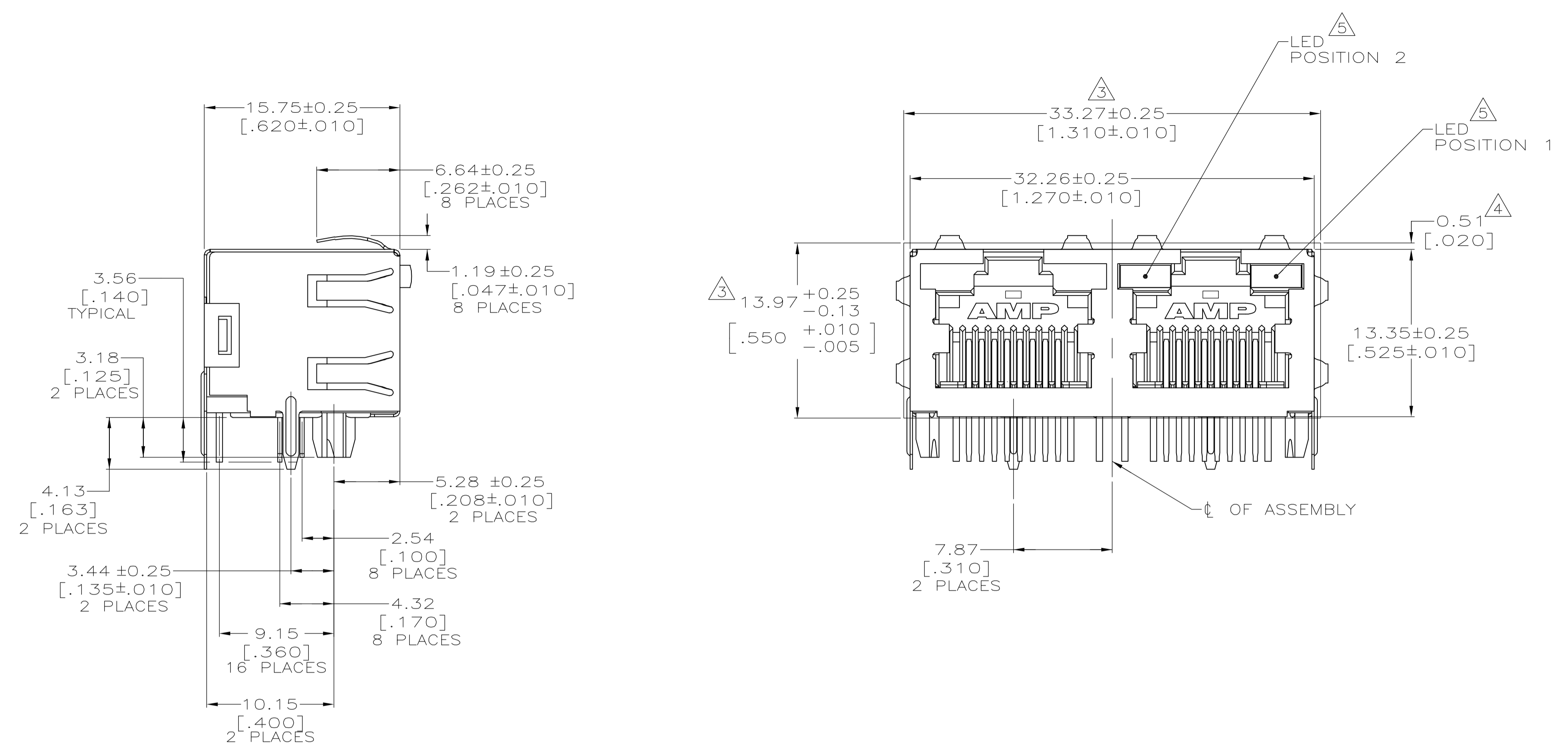
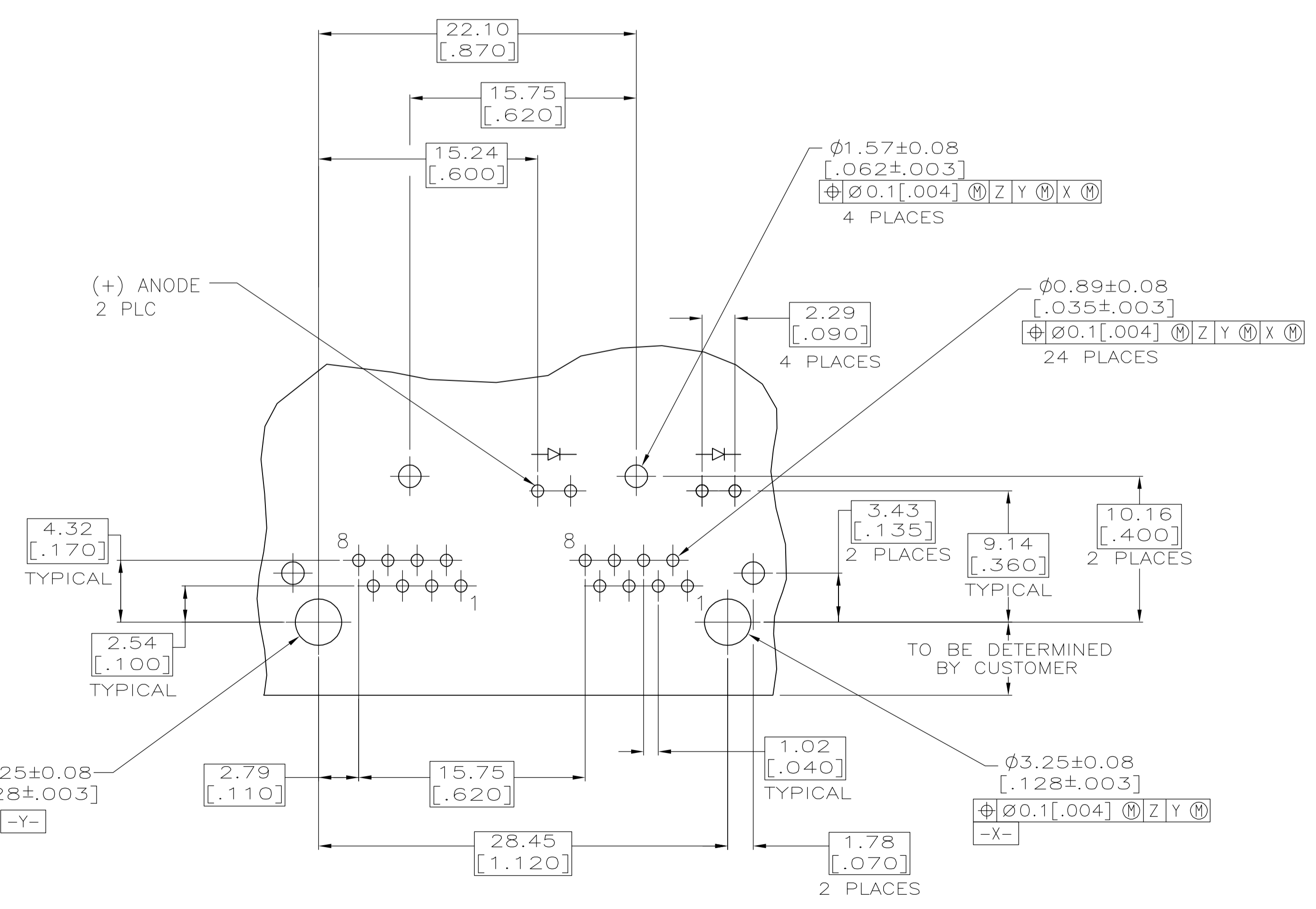


LOC		DIST		REVISIONS			
GP	00	P	L/R	DESCRIPTION	DATE	DWN	APVD
A	RELEASED				11AUG06	RG	JW



- 1 MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm [.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27μm[.000050] MINIMUM SATIN NICKEL WITH 2.03μm[.000080] MINIMUM TIIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89μm[.00034] THK. Sn/Cu OVER 2.03μm[.000080] THK. Ag OVER 1.02 μm[.000040] THK. Cu OVER 3.56μm[.00014] THK. Ni OVER 1.02μm[.000040] THK. Cu UNDERPLATE.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 SUGGESTED PANEL OPENING DIMENSIONS.
- 4 SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- 5 SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

YELLOW	GREEN	1888612-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN R GRZYBOWSKI 11AUG06		Tyco Electronics Corporation	
DIMENSIONS: mm		CHK J.WESTMAN 11AUG06		Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD J.WESTMAN 11AUG06		NAME	
0 PLC ± -		PRODUCT SPEC		INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND, WITH LEDS	
1 PLC ± -		APPLICATION SPEC		SIZE	
2 PLC ± 0.25[.01]		114-2154		CAGE CODE	
3 PLC ± 0.13[.005]		WEIGHT		DRAWING NO	
4 PLC ± -		A1 00779		RESTRICTED TO	
ANGLES ± -		CUSTOMER DRAWING		SCALE 4:1	
FINISH		1888612		SHEET 1 OF 1	
				REV A	